BOARD CHARACTERISTICS

Copper Layer Count:	4	Board Thickness:	66.30 mils
Board overall dimensions:	5530.00 mils x 5450.00 mils		
Min track/spacing:	12.00 mils / 12.00 mils	Min hole diameter:	11.81 mils
Copper Finish:	None	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mils)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mils	Not specified	1	0
F.Paste	Top Solder Paste		0 mils		1	0
F.Mask	Top Solder Mask	Not specified	0.3937 mils	Not specified	3.3	0
F.Cu	copper		1.37795 mils		1	0
Dielectric	core	FR4	20 mils	Not specified	4.5	0.02
In1.Cu	copper		1.37795 mils		1	0
Dielectric	prepreg	FR4	20 mils	Not specified	4.5	0.02
In2.Cu	copper		1.37795 mils		1	0
Dielectric	core	FR4	20 mils	Not specified	4.5	0.02
B.Cu	copper		1.37795 mils		1	0
B.Mask	Bottom Solder Mask	Not specified	0.3937 mils	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mils		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mils	Not specified	1	0

Drill Map:
× 0.711mm / 0.0280'' (10 holes)
○ 1.000mm / 0.0394'' (137 holes)
+ 1.092mm / 0.0430'' (205 holes)
□ 3.200mm / 0.1260'' (2 holes) (not plated)
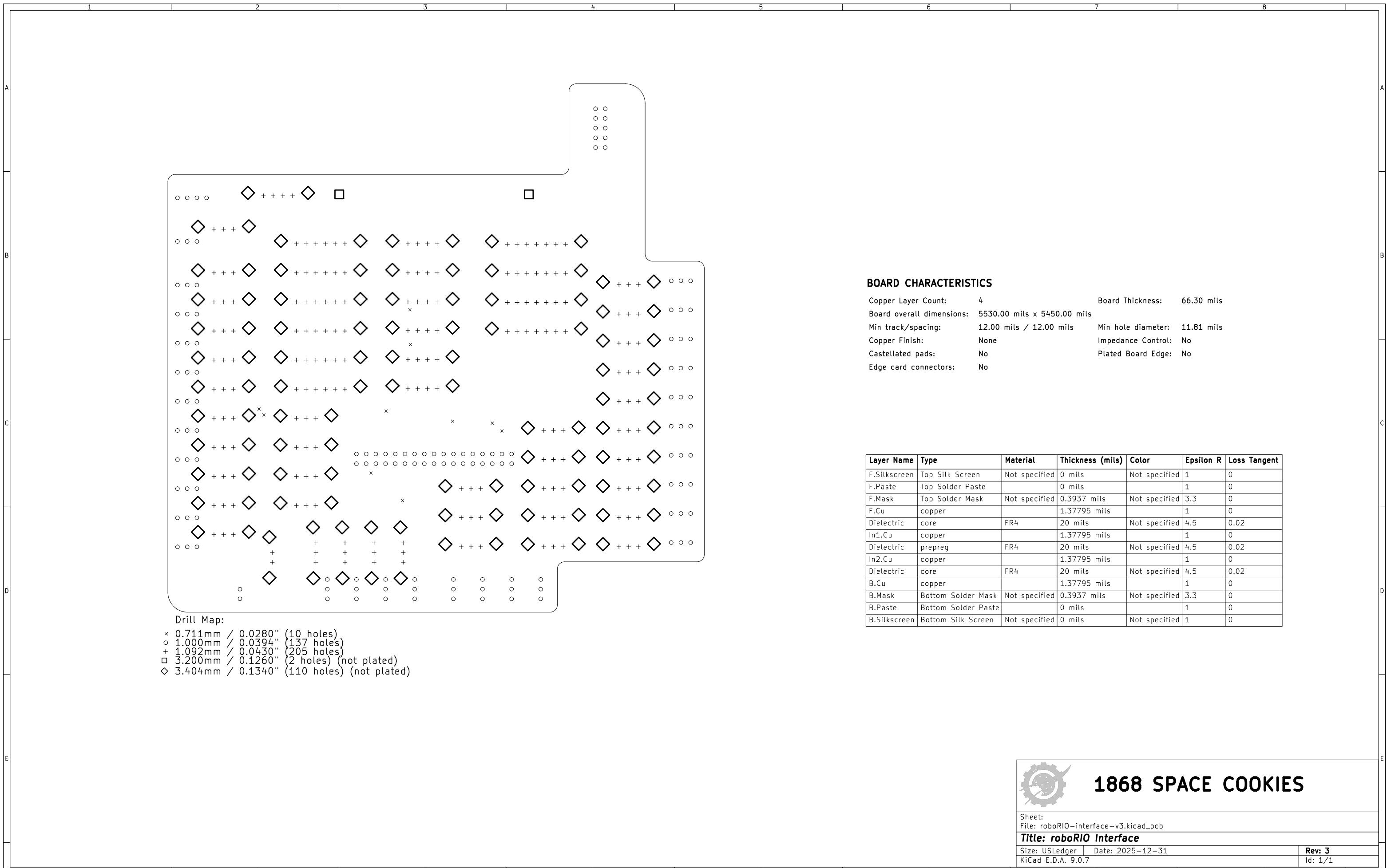◇ 3.404mm / 0.1340'' (110 holes) (not plated)

1868 SPACE COOKIES

Sheet:
File: roboRIO-interface-v3.kicad_pcb
Title: roboRIO Interface
Size: USLedger | Date: 2025-12-31 | Rev: 3
KiCad E.D.A. 9.0.7 | Id: 1/1